Compliant with IEC 62474/ D9.00

ICROCHIP Semiconductor Device	(A6X) 008 DFN-S 6x5 mm Matte Tin	Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)				JEDEC 97 Product Marking and/or Pkg. Labeling e3	
- Connocination Bories	- 1 ypo. IIII	"Contained In"	% Lotal	Т	_			1		
Basic Substance	CAS Number	Sub-Component	Weight	mg/part	ppm	37.77	(mg) Total	Mold Compound	% ot Total Weight	49.12
Silica, fused	60676-86-0	Mold Compound	44.208	33.996	442,080		Silica, fused	60676-86-0	90.00	
Epoxy Resin (NLP # 500-033-5)	Trade Secret	Mold Compound	2.382	1.832	23,823	Epox	Resin (NLP # 500-033-5)	Trade Secret	4.85	1
Phenolic Resin	Trade Secret	Mold Compound	2.382	1.832	23,823	-	Phenolic Resin	Trade Secret	4.85	1
Carbon Black	1333-86-4	Mold Compound	0.147	0.113	1,474		Carbon Black	1333-86-4	0.30	
Copper	7440-50-8	Lead Frame	42.960	33.036	429,600	•		Total	100.00	
Tin	7440-31-5	Lead Frame	0.110	0.085	1,103	33.91	(mg) Total	Lead Frame	% of Total Weight	44.1
Silver	7440-22-4	Lead Frame	0.840	0.646	8,401		Copper	7440-50-8	97.42	
Zinc	7440-66-6	Lead Frame	0.079	0.061	794		Tin	7440-31-5	0.25	1
Chromium	7440-47-3	Lead Frame	0.110	0.085	1.103		Silver	7440-22-4	1.91	1
Silver	7440-22-4	Die Attach	0.320	0.246	3,198		Zinc	7440-66-6	0.18	1
Acrylate resins Proprietary	Trade Secret	Die Attach	0.074	0.057	738		Chromium	7440-47-3	0.25	1
Treated silica	Trade Secret	Die Attach	0.008	0.006	82	,	<u> </u>	Total	100.00	9
Heterocyclic organic compound	Trade Secret	Die Attach	0.008	0.006	82	0.32	(mg) Total	Die Attach	% of Total Weight	0.41
Silicon	7440-21-3	Chip (Die)	2.870	2,207	28,700	0.02	Silver	7440-22-4	78	1 0.71
Gold	7440-57-5	Wire Bond	0.170	0.131	1,700		Acrylate resins Proprietary	Trade Secret	18	ł
Tin	7440-31-5	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	3.330	2.561	33,300		Treated silica	Trade Secret	2	l
	7440-31-3	TOTALS:	100.000	76.900	1.000.000	11-4-	rocyclic organic compound	Trade Secret	2	
			100.000	76.900	1,000,000	Hete	rocyclic organic compound	Total	100.00	<u> </u>
	0.0769	g Total Mass						lotai	100.00	
s semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March 5) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero) mpliance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data.					2.21	Total (mg)	Chip (Die)	% of Total Weight	2.87	
liance with the above EU Directives has been verified	via internal design contro	s, supplier declarations, and /or analytical test data.					Doped Silicon	7440-21-3	100	
porated's knowledge and belief as of the date of this do below the threshold of regulatory concern for any reg	locument, there is no cred	an intentional ingredient in the semiconductor device and,			nnoioav			Total		
		e.		hemical subst	ance, if any,				100.00	
	lammability standard for p			hemical subst	ance, if any,	0.13	(mg) Total	Wire Bond	% of Total Weight	
ing compounds used by Microchip meet the UL94 V0 fl /ul.com/global/eng/pages/offerings/industries/chemica	lammability standard for pals/plastics/	e.	obtain a test r	hemical subst	,	0.13	(mg) Total Doped Gold		% of Total Weight	
ing compounds used by Microchip meet the UL94 V0 fl /ul.com/global/eng/pages/offerings/industries/chemica rotective "tubes" in which the specific product is ship in "reels" may be made from PVC plastic. Ichip Technology Incorporated believes the information original packing materials is true and correct to the best eleteness and accuracy of data in this form because it I nation is often protected from disclosure as trade secr	lammability standard for p als/plastics/ pped are made from polyvi on in this form concerning ist of its knowledge and be has been compiled based rets and some information parts and the average weig	e. lastics. You can access the UL iQTM family of databases to myl chloride (PVC) plastic. "Window envelopes" used to ho substances restricted by RoHS in Microchip Technology In lief, as of the date listed in this form. Microchip Technology on the ranges provided in Material Safety Data Sheets provided in the total state that sheets provided in the ranges provided by subcontract assemblers a ht of anticipated significant toxic metals components. These	o obtain a test r Id the packing corporated's so y Incorporated ided by raw ma nd raw materia	hemical subst eport at slip on the our emiconductor cannot guaral terial supplier I suppliers. In	devices in ntee the rs. Supplier formation is	0.13		Wire Bond	% of Total Weight	
ing compounds used by Microchip meet the UL94 V0 fl /ul.com/global/eng/pages/offerings/industries/chemica rotective "tubes" in which the specific product is ship in "reels" may be made from PVC plastic. chip Technology Incorporated believes the information original packing materials is true and correct to the bestleteness and accuracy of data in this form because it I mation is often protected from disclosure as trade secret ded only as estimates of the average weight of these p pants, metals, and non-metal materials contained within schip Technology Incorporated does not provide any we	lammability standard for pals/plastics/ pped are made from polyvi on in this form concerning set of its knowledge and be shas been compiled based retars and some information that is a verage weig in silicon devices (silicon varranty, express or implie	e. lastics. You can access the UL iQTM family of databases to myl chloride (PVC) plastic. "Window envelopes" used to ho substances restricted by RoHS in Microchip Technology In lief, as of the date listed in this form. Microchip Technology on the ranges provided in Material Safety Data Sheets provided in the total state that sheets provided in the ranges provided by subcontract assemblers a ht of anticipated significant toxic metals components. These	obtain a test r Id the packing corporated's so y incorporated ided by raw ma nd raw materia se estimates do on. The exclus	hemical subst eport at slip on the out emiconductor cannot guarat terial supplier I suppliers. Int not include to	devices in ntee the rs. Supplier formation is race levels	0.13		Wire Bond 7440-57-5	% of Total Weight	0.17
ing compounds used by Microchip meet the UL94 V0 fl /ul.com/global/eng/pages/offerings/industries/chemica /ortective "tubes" in which the specific product is ship in "reels" may be made from PVC plastic. In the production or production	lammability standard for pals/plastics/ pped are made from polyvi on in this form concerning ist of its knowledge and be has been compiled based rets and some information parts and the average weig in silicon devices (silicon varranty, express or implie I and its subsidiaries are c changes to Material Conte he users' reliance on the ir	e. lastics. You can access the UL iQTM family of databases to myl chloride (PVC) plastic. "Window envelopes" used to ho substances restricted by RoHS in Microchip Technology In lief, as of the date listed in this form. Microchip Technology on the ranges provided in Material Safety Data Sheets provided in the value of	obtain a test r Id the packing corporated's si y incorporated idded by raw ma ind raw materia se estimates do on. The exclus ale. These are j ect or indirect,	hemical subst eport at slip on the out emiconductor cannot guarai tetrial supplier I suppliers. In o not include to ive, limited pro- provided in Mi	devices in ntee the rs. Supplier formation is race levels oduct icrochip's		Doped Gold	Wire Bond 7440-57-5 Total Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1	% of Total Weight 100 100.00	0.17

Au 10:39 AM : 8/17/2015